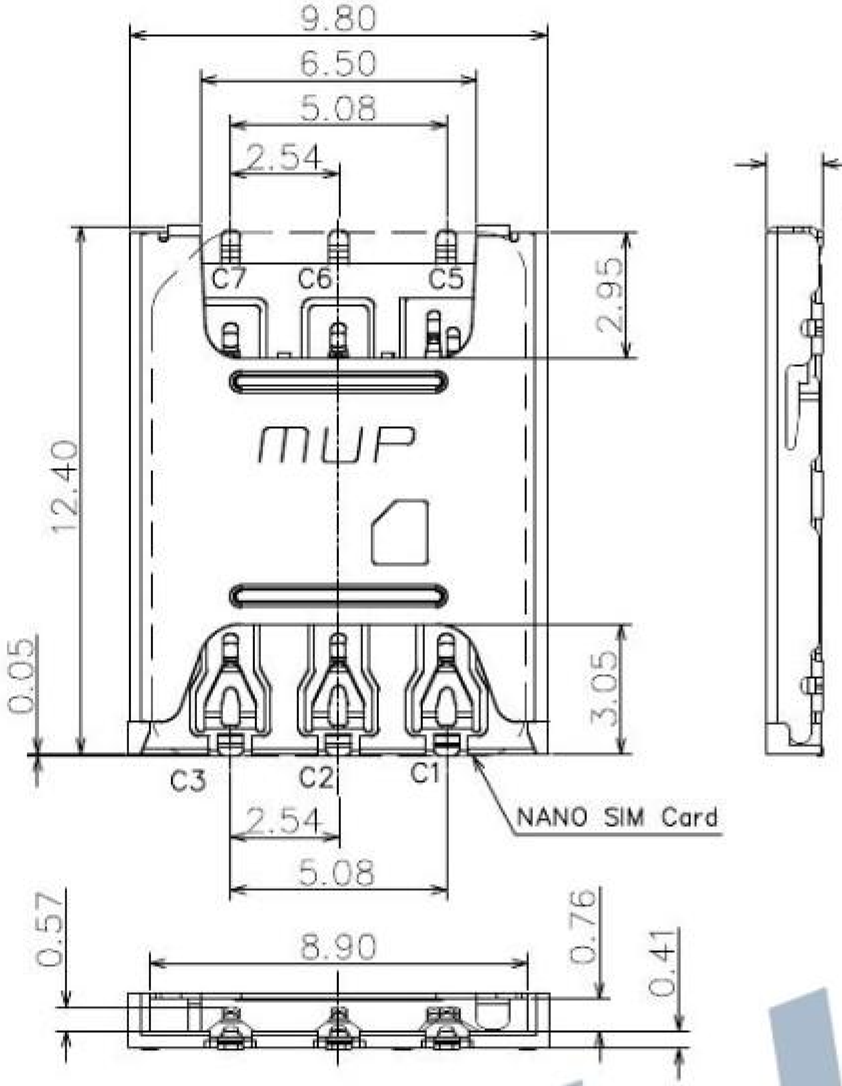
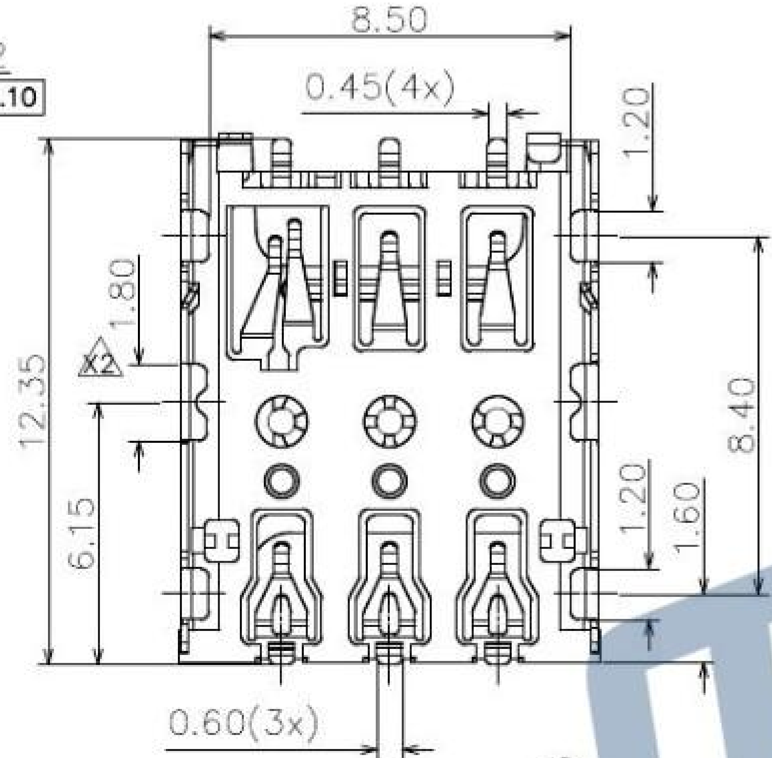
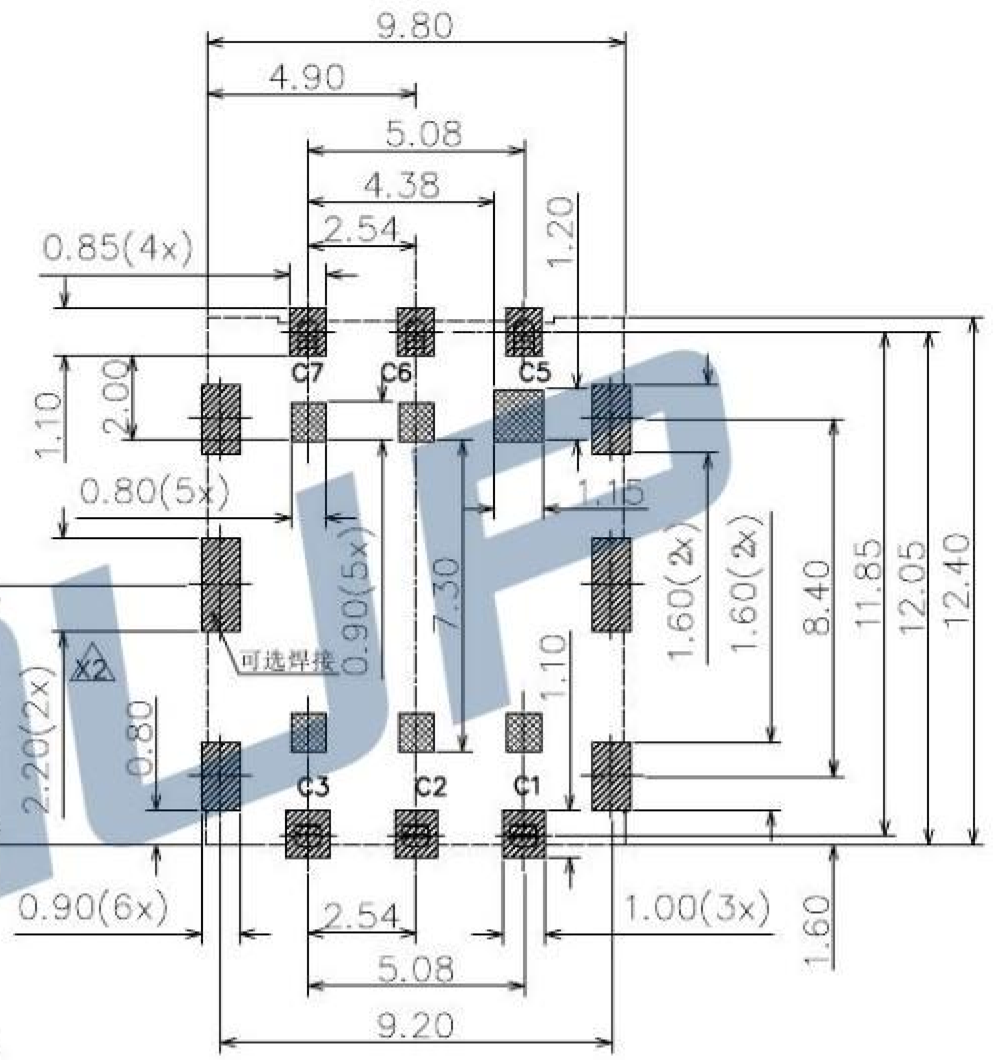
REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Henry Apr.10.2014
X2					

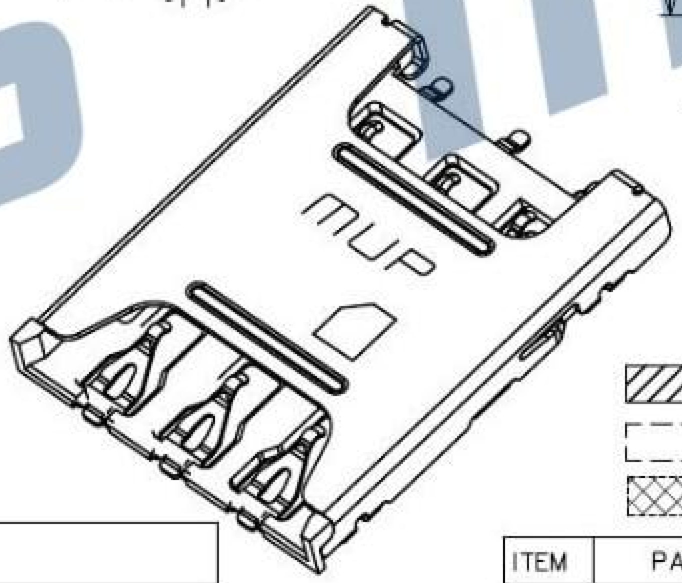






RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

▨ PAD AREA
┆ CONNECTOR OUTLINE
▩ NO PATTERN AND VIA HOLE IN THIS AREA



TECHNICAL CHARACTERISTICS

1.General Characteristics
Dimensions: 12.40LX9.80WX1.35H mm
Weight: Approx 0.50±0.2g
Durability: 1,500 cycles min.

2.Electrical Characteristics
Contact resistance: 50mΩ typical,
100mΩ max
Insulation resistance: >1000MΩ/500V DC

3.Solderability
Vaporphase: 215°C,30sec.Max
IR reflow: 250°C,5sec.Max
Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics
Operating temperature: −40°C~+85°C
Operating humidity: 10%~+95%RH

NANO SIM CARD

Pin No.	ASSIGNMENT
C1	VCC(SUPPLY VOLTAGE)
C2	RST(RESET SIGNAL)
C3	CLK(COLCK SIGNAL)
C5	GND
C6	VPP(VARIABLE SUPPLY VOLTAGE)
C7	I/O(DATA INPUT/OUTPUT

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	±0.35	X°	±5°
X.X	±0.25	X.X°	±4°
X.XX	±0.15	X.XX°	±3°
X.XXX	±0.10	X.XXX°	±2°

PROJ.	UNIT	SCALE
	mm	1:1

CUSTOMER DRAWING

MUP® MUP INDUSTRIAL CO.,LTD.

NAME:	**NANO-SIM Card Connector**
MODEL NO:	**MUP-C782-3**
TYPE :	**H1.35mm 6PIN Without Switch Pin**

DRAWN	Henry Mar.12.2019	DWG NO.: DWG-MUP-C782-3	
CHECKED	Henry Mar.12.2019	SHEET	REVISION
APPROVAL	Simon Mar.12.2019	1/1	X1

Pb RoHS PROCESS COMPLIANT